INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. 50395-126		SERIAL NO. Divisional of 09/543,356	
				APPLICANT Keigo OBA	ATA, et al.		17.00
(PTO-1449)				FILING DATE January 7, 2002		GROUP /775 TO Not yet assigned	
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.